

**REMARKS**

By the above amendments, a number of amendment have been made to the claimed subject matter so as to present a preferred scope of coverage.

Attached hereto is a marked-up version of the changes made to the claims by the current Preliminary Amendment. The attached page is captioned "**Version with Markings to Show Changes Made**".

An early and favorable action on the merits is respectfully requested.

Respectfully submitted,

Yutaka WADA et al.

By: 

Nils E. Pedersen

Registration No. 33,145

Attorney for Applicants

NEP/krl  
Washington, D.C. 20006-1021  
Telephone (202) 721-8200  
Facsimile (202) 721-8250  
April 11, 2002

THE COMMISSIONER IS AUTHORIZED  
TO CHARGE ANY DEFICIENCY IN THE  
FEES FOR THIS PAPER TO DEPOSIT  
ACCOUNT NO. 23-0975

Version with Markings to  
Show Changes Made

## CLAIMS

✓ 1. A method for polishing an object having raised and depressed pattern thereon to produce a flat and mirror polished surface by using an abrading plate, said method comprising:

*Surface made of abrasive particles and liquid.*

polishing said object by supplying a liquid not containing any abrasive particles for a determined time period; and

10 further polishing said object by supplying abrasive particles so as to perform additional removal of a surface material to uniformly remove a specific film thickness.

✓ 2. A method according to claim 1, wherein said additional removal of a surface material is performed with said abrading <sup>surface</sup> plate by supplying a liquid not containing any abrasive particles for a specific duration, followed by additional polishing by supplying a slurry containing abrasive particles to said surface to be polished.

20 3. A method according to claim 1, wherein said additional removal of a surface material is performed by:

polishing using an abrading plate and supplying a liquid not containing any abrasive particles for a specific

25 time duration, and

additional polishing while concurrently dressing said abrading <sup>surface</sup> plate with a liquid not containing abrasive

particles, thereby to generate free abrasive particles therefrom.

4. A method according to claim 1, wherein said  
5 additional removal of a surface material is performed by:  
    {polishing using an abrading plate and supplying a  
liquid not containing any abrasive particles for a specific  
time duration, and  
    additional} polishing using a polishing cloth and a  
10 slurry containing abrasive particles.

5. A polishing apparatus for polishing a surface of  
    {a substrate} <sup>an</sup> object {having fine raised and depressed  
structures thereon by pressing said surface to an abrading  
15 surface of an abrading plate}, said apparatus comprising:  
    a holder for holding said {substrate} object;  
    an abrading {plate holder for holding said abrading  
plate}; *surface comprising abrasive particles and a binder*  
    a mechanism for pressing said surface of said  
20 {substrate} object to said abrading surface {of said abrading  
plate} while producing a sliding motion over a polishing  
interface;  
    a device for supplying a liquid not containing  
abrasive particles to said polishing interface; and  
25 a surface material removal device for performing  
additional material removal by supplying abrasive particles,  
said device integrally mounted in said polishing apparatus.

6. An apparatus according to claim 5, wherein said surface material removal device is a device for supplying a slurry containing abrasive particles to said polishing interface.

5

7. An apparatus according to claim 5, wherein said surface material removal device is a device for dressing said [surface of said] abrading [plate] <sup>surface</sup> so as to [produce] <sup>release</sup> abrasive particles.

10

*from said abrading surface*

8. An apparatus according to claim 5, wherein said apparatus is provided with a first polishing means to perform polishing while supplying a liquid not containing abrasive particles to said polishing interface; and a second polishing means to perform polishing while supplying a slurry containing abrasive particles to said polishing interface.

20

9. A method for polishing a surface of a workpiece, comprising:

first polishing the surface of the workpiece with an abrasive surface comprising abrasive particles and a binder binding said abrasive particles in the presence of a liquid; and

25

finish polishing the surface of the workpiece with a polishing surface that comprises a buffing pad in the presence of a slurry.